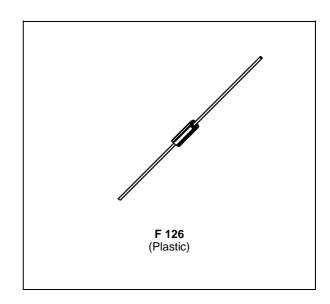
BYT 11-600 →1000

FAST RECOVERY RECTIFIER DIODES

- SOFT RECOVERY
- VERY HIGH VOLTAGE
- SMALL RECOVERY CHARGE



APPLICATIONS

- ANTISATURATION DIODES FOR TRANSIS-TOR BASE DRIVE
- SNUBBER DIODES

ABSOLUTE RATINGS (limiting values)

Symbol	Parameter	Value	Unit	
I _{FRM}	Repetive Peak Forward Current	20	Α	
I _{F (AV)}	Average Forward Current *	1	А	
I _{FSM}	Surge non Repetitive Forward Current	t _p = 10ms Sinusoidal	35	А
P _{tot}	Power Dissipation *	1.25	W	
T _{stg} Tj	Storage and Junction Temperature Range	- 55 to + 150 - 55 to + 150	°C	
TL	Maximum Lead Temperature for Soldering during from Case	230	°C	

Symbol	Parameter		Unit		
	T di diffetei	600	800	1000	
V_{RRM}	Repetitive Peak Reverse Voltage	600	800	1000	V

THERMAL RESISTANCE

Symbol	Parameter	Value	Unit
R _{th (j - a)}	Junction-ambient*	60	°C/W

^{*} On infinite heatsink with 10mm lead length.

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ELECTRICAL CHARACTERISTICS

STATIC CHARACTERISTICS

Synbol		Test Conditions	Min.	Тур.	Max.	Unit
I _R	T _j = 25°C	$V_R = V_{RRM}$			20	μΑ
V _F	T _j = 25°C	I _F = 1A			1.3	٧

RECOVERY CHARACTERISTICS

Symbol		Test	Min.	Тур.	Max.	Unit		
t _{rr}	T _j = 25°C	$I_{F} = 0.5A$	$I_R = 1A$	$I_{rr} = 0.25A$			100	ns

To evaluate the conduction losses use the following equations:

 $V_F = 1.1 + 0.075 I_F$

 $P = 1.1 \times I_{F(AV)} + 0.075 I_{F}^{2}(RMS)$

Figure 1. Maximum average power dissipation versus average forward current.

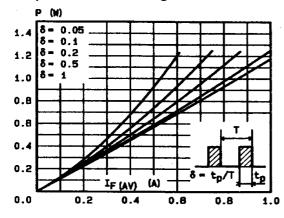


Figure 2. Average forward current versus ambient temperature.

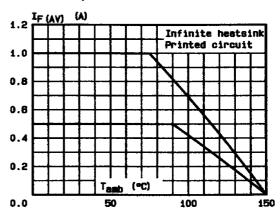
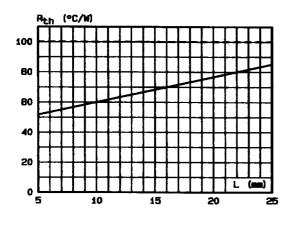


Figure 3. Thermal resistance versus lead length.



Mounting n°1
INFINITE HEATSINK

Mounting n°2 PRINTED CIRCUIT

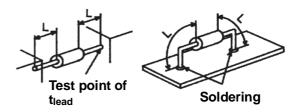


Figure 4. Transient thermal impedance junction-ambient for mounting n^2 versus pulse duration (L = 10 mm).

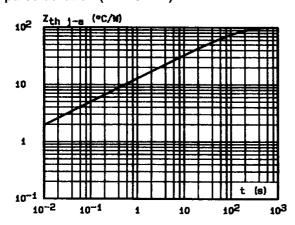


Figure 5. Peak forward current versus peak forward voltage drop (maximum values).

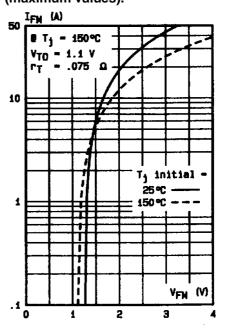


Figure 6. Capacitance versus reverse applied voltage

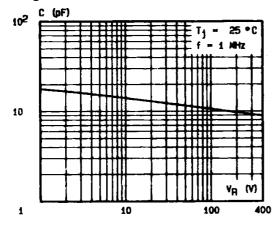
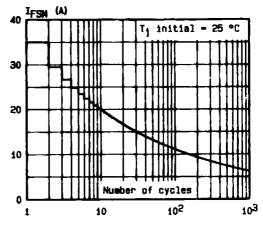
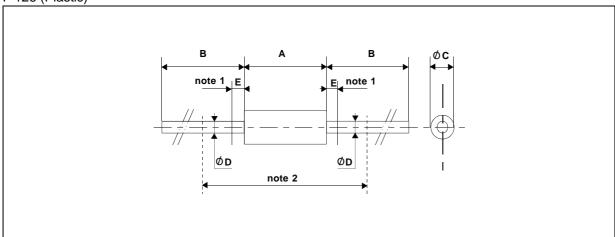


Figure 7. Non repetitive surge peak current versus number of cycles



PACKAGE MECHANICAL DATA

F 126 (Plastic)



	DIMENSIONS					
REF. Millimeters		Inches		NOTES		
	Min.	Max.	Min.	Max.		
Α	6.05	6.35	0.238	0.250	1 - The lead diameter Ø D is not controlled over zone E	
В	26		1.024			
ØC	2.95	3.05	0.116	0.120	2 - The minimum axial lengh within which the device may be placed with its leads bent at right angles is 0.59"(15 mm)	
Ø D	0.76	0.86	0.029	0.034	phaced with its leads bent at right angles is 0.59 (15 min)	
Е		1.27		0.050		

Cooling method: by convection (method A) Marking: type number ring at cathode end Weight: 0.4g

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